

# NDF05N50Z, NDD05N50Z

## N-Channel Power MOSFET 500 V, 1.5 $\Omega$

### Features

- Low ON Resistance
- Low Gate Charge
- ESD Diode-Protected Gate
- 100% Avalanche Tested
- 100% Rg Tested
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

### ABSOLUTE MAXIMUM RATINGS ( $T_C = 25^\circ\text{C}$ unless otherwise noted)

Rating	Symbol	NDF	NDD	Unit
Drain-to-Source Voltage	$V_{DSS}$	500		V
Continuous Drain Current $R_{\theta JC}$	$I_D$	5.5 (Note 1)	4.7	A
Continuous Drain Current $R_{\theta JC}$ , $T_A = 100^\circ\text{C}$	$I_D$	3.5 (Note 1)	3	A
Pulsed Drain Current, $V_{GS} @ 10\text{ V}$	$I_{DM}$	20	19	A
Power Dissipation $R_{\theta JC}$	$P_D$	30	83	W
Gate-to-Source Voltage	$V_{GS}$	$\pm 30$		V
Single Pulse Avalanche Energy, $I_D = 5.0\text{ A}$	$E_{AS}$	130		mJ
ESD (HBM) (JESD22-A114)	$V_{ESD}$	3000		V
RMS Isolation Voltage ( $t = 0.3\text{ sec.}$ , R.H. $\leq 30\%$ , $T_A = 25^\circ\text{C}$ ) (Figure 17)	$V_{ISO}$	4500		V
Peak Diode Recovery (Note 2)	$dV/dt$	4.5		V/ns
MOSFET $dV/dt$	$dV/dt$	60		V/ns
Continuous Source Current (Body Diode)	$I_S$	5		A
Maximum Temperature for Soldering Leads	$T_L$	260		$^\circ\text{C}$
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to 150		$^\circ\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

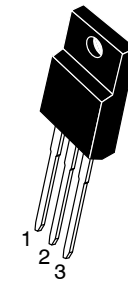
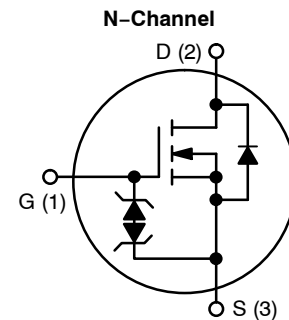
1. Limited by maximum junction temperature
2.  $I_S = 4.4\text{ A}$ ,  $di/dt \leq 100\text{ A}/\mu\text{s}$ ,  $V_{DD} \leq BV_{DSS}$ ,  $T_J = +150^\circ\text{C}$



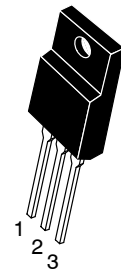
ON Semiconductor®

<http://onsemi.com>

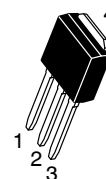
$V_{DSS}$	$R_{DS(on)} (MAX) @ 2.2\text{ A}$
500 V	1.5 $\Omega$



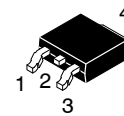
NDF05N50ZG  
TO-220FP  
CASE 221D



NDF05N50ZH  
TO-220FP  
CASE 221AH



NDD05N50Z-1G  
IPAK  
CASE 369D



NDD05N50ZT4G  
DPAK  
CASE 369AA

### ORDERING AND MARKING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 7 of this data sheet.

# NDF05N50Z, NDD05N50Z

## THERMAL RESISTANCE

Parameter	Symbol	Value	Unit
Junction-to-Case (Drain)	NDF05N50Z	4.2	°C/W
	NDD05N50Z	1.5	
Junction-to-Ambient Steady State	(Note 3) NDF05N50Z	50	
	(Note 4) NDD05N50Z	38	
	(Note 3) NDD05N50Z-1	80	

3. Insertion mounted

4. Surface mounted on FR4 board using 1" sq. pad size, (Cu area = 1.127 in sq [2 oz] including traces).

## ELECTRICAL CHARACTERISTICS (T<sub>J</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Test Conditions	Min	Typ	Max	Unit
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### OFF CHARACTERISTICS

Drain-to-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 1 mA	500			V
Breakdown Voltage Temperature Coefficient	ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	Reference to 25°C, I <sub>D</sub> = 1 mA		0.6		V/°C
Drain-to-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V	25°C		1	μA
			150°C		50	
Gate-to-Source Forward Leakage	I <sub>GSS</sub>	V <sub>GS</sub> = ±20 V			±10	μA

### ON CHARACTERISTICS (Note 5)

Static Drain-to-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 2.2 A		1.25	1.5	Ω
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 50 μA	3.0	3.9	4.5	V
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 2.5 A		3.5		S

### DYNAMIC CHARACTERISTICS

Input Capacitance (Note 6)	C <sub>iss</sub>	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1.0 MHz	421	530	632	pF
Output Capacitance (Note 6)	C <sub>oss</sub>		50	68	80	
Reverse Transfer Capacitance (Note 6)	C <sub>rss</sub>		8	15	25	
Total Gate Charge (Note 6)	Q <sub>g</sub>	V <sub>DD</sub> = 250 V, I <sub>D</sub> = 5 A, V <sub>GS</sub> = 10 V	9	18.5	28	nC
Gate-to-Source Charge (Note 6)	Q <sub>gs</sub>		2	4	6	
Gate-to-Drain ("Miller") Charge (Note 6)	Q <sub>gd</sub>		5	10	15	
Plateau Voltage	V <sub>GP</sub>			6.5		V
Gate Resistance	R <sub>g</sub>		1.5	4.5	8	Ω

### RESISTIVE SWITCHING CHARACTERISTICS

Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 250 V, I <sub>D</sub> = 5 A, V <sub>GS</sub> = 10 V, R <sub>G</sub> = 5 Ω		11		ns
Rise Time	t <sub>r</sub>			15		
Turn-Off Delay Time	t <sub>d(off)</sub>			24		
Fall Time	t <sub>f</sub>			14		

### SOURCE-DRAIN DIODE CHARACTERISTICS (T<sub>C</sub> = 25°C unless otherwise noted)

Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> = 5 A, V <sub>GS</sub> = 0 V			1.6	V
Reverse Recovery Time	t <sub>rr</sub>	V <sub>GS</sub> = 0 V, V <sub>DD</sub> = 30 V, I <sub>S</sub> = 5 A, di/dt = 100 A/μs		255		ns
Reverse Recovery Charge	Q <sub>rr</sub>			1.25		μC

5. Pulse Width ≤ 380 μs, Duty Cycle ≤ 2%.

6. Guaranteed by design.

# NDF05N50Z, NDD05N50Z

## TYPICAL CHARACTERISTICS

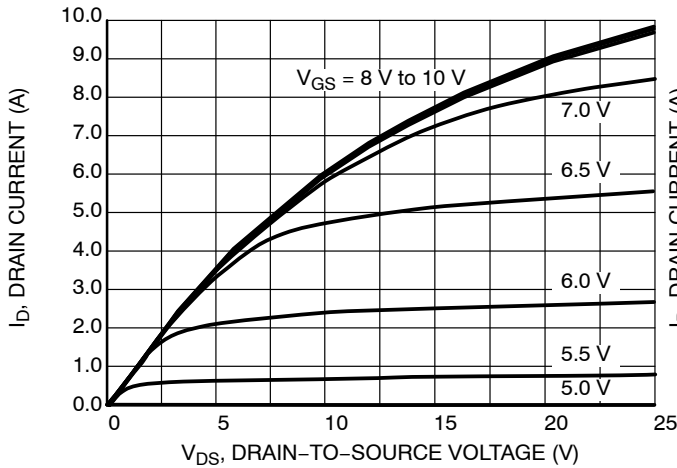


Figure 1. On-Region Characteristics

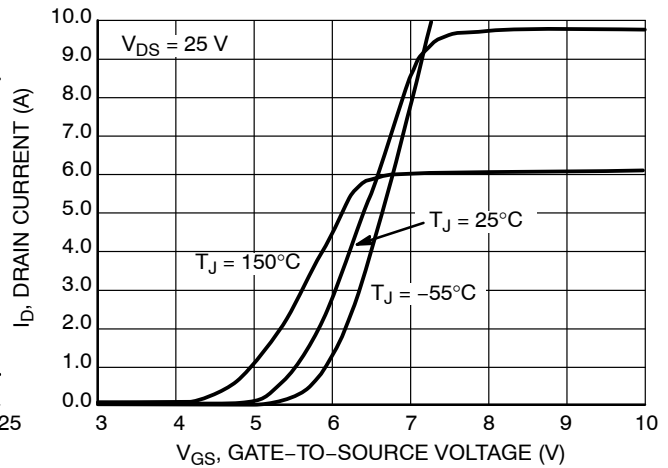


Figure 2. Transfer Characteristics

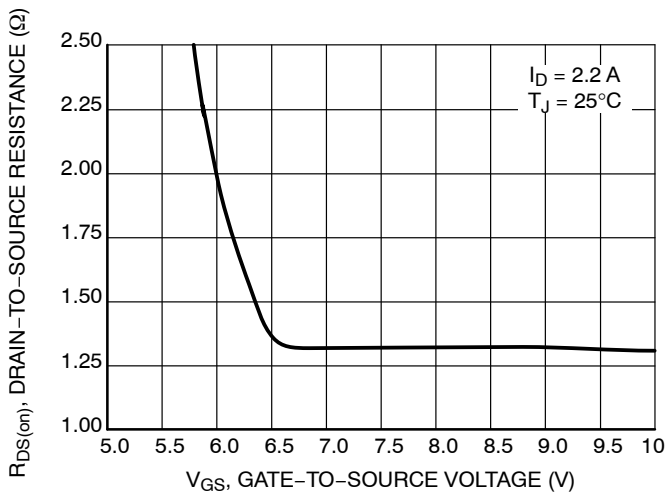


Figure 3. On-Region versus Gate-to-Source Voltage

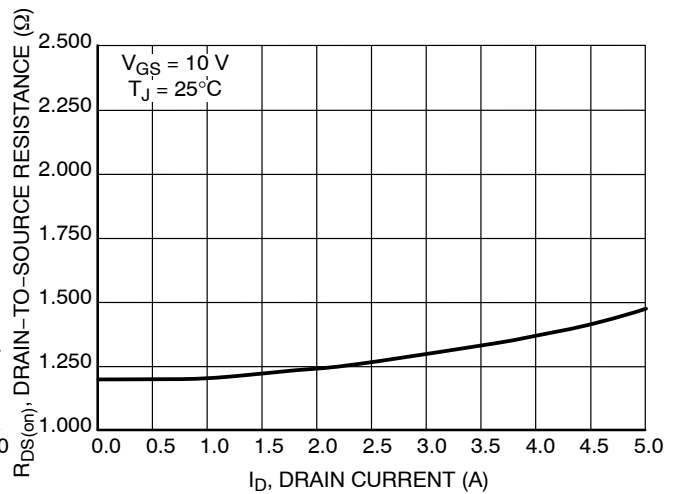


Figure 4. On-Resistance versus Drain Current and Gate Voltage

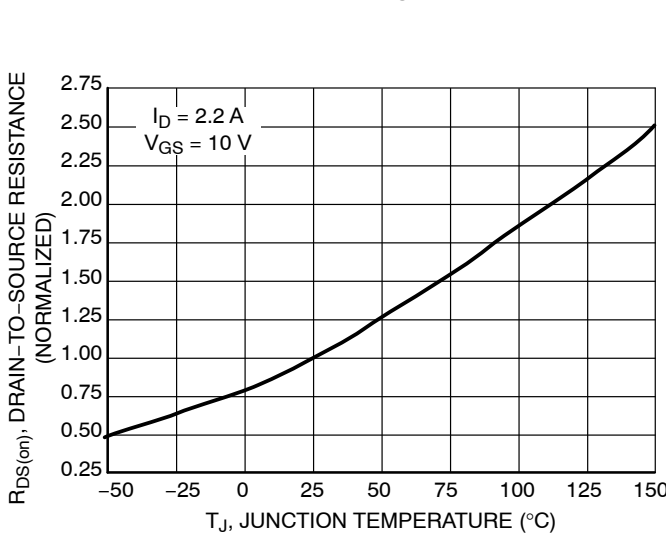


Figure 5. On-Resistance Variation with Temperature

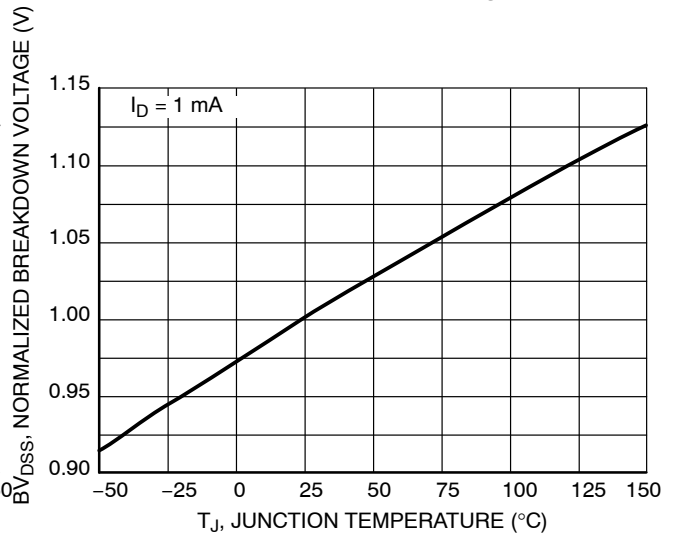


Figure 6.  $BV_{DSS}$  Variation with Temperature

# NDF05N50Z, NDD05N50Z

## TYPICAL CHARACTERISTICS

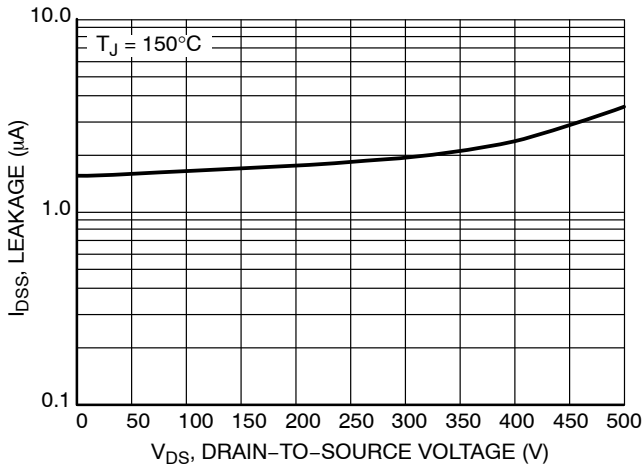


Figure 7. Drain-to-Source Leakage Current versus Voltage

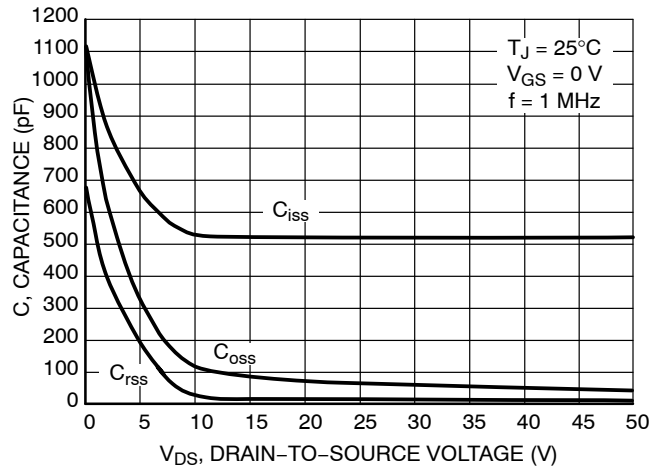


Figure 8. Capacitance Variation

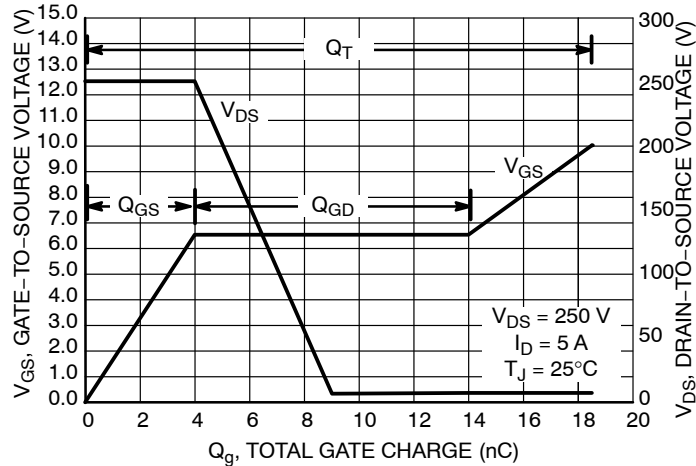


Figure 9. Gate-to-Source Voltage and Drain-to-Source Voltage versus Total Charge

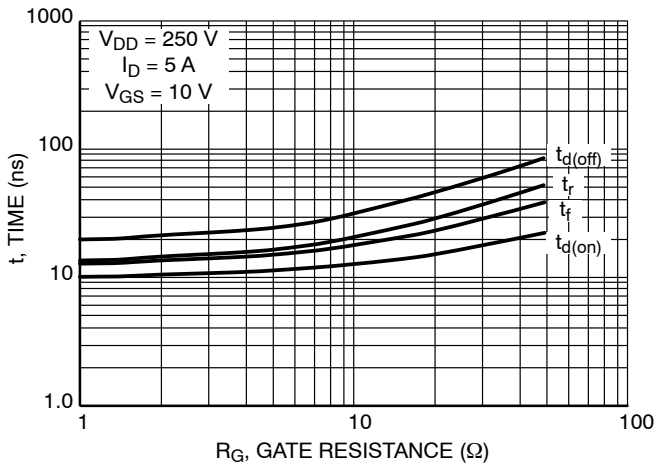


Figure 10. Resistive Switching Time Variation versus Gate Resistance

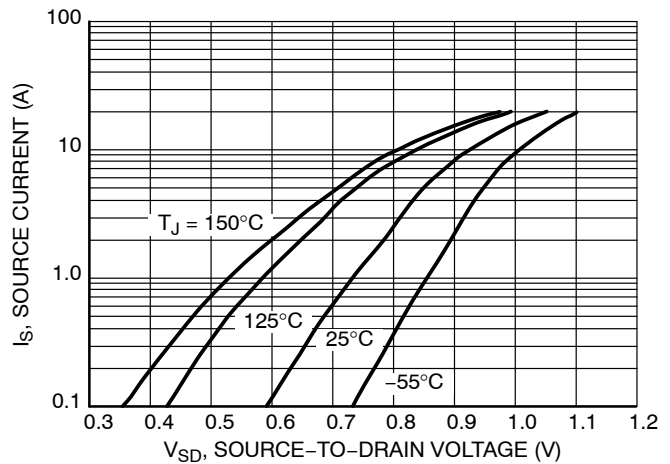
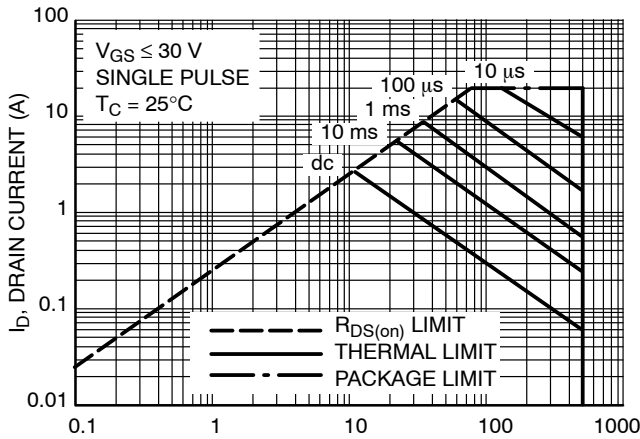


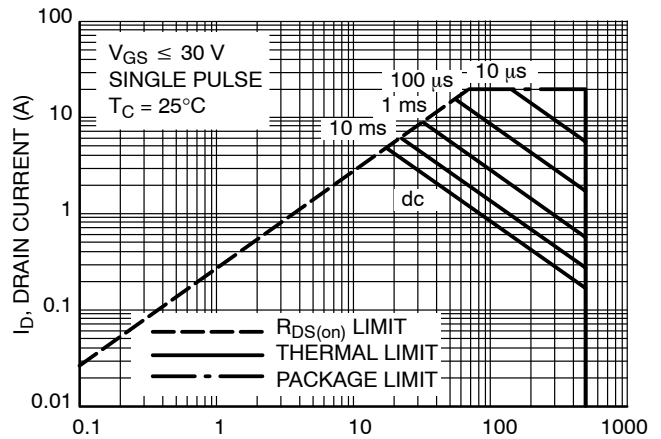
Figure 11. Diode Forward Voltage versus Current

# NDF05N50Z, NDD05N50Z

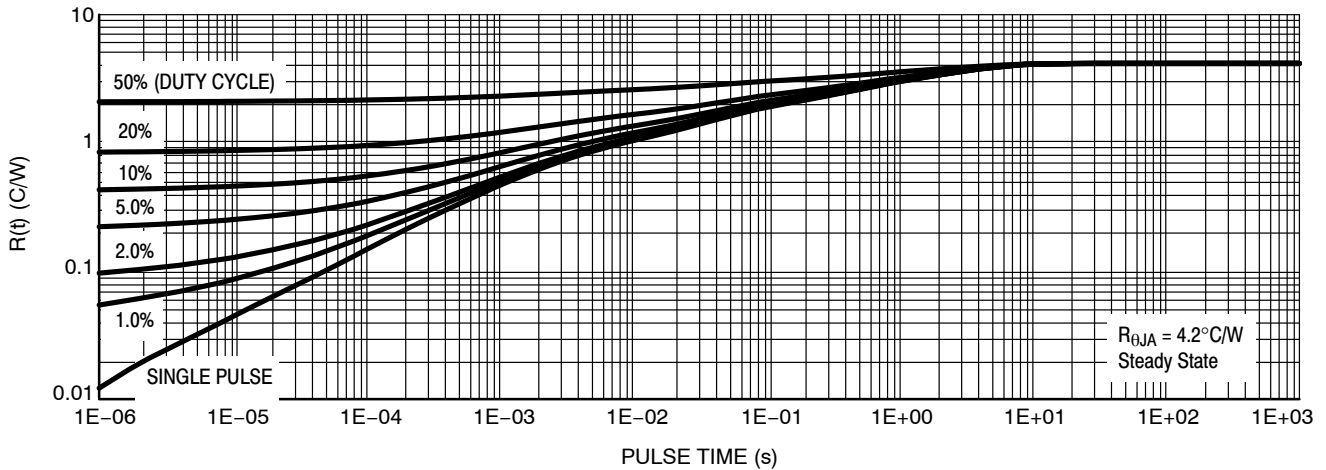
## TYPICAL CHARACTERISTICS



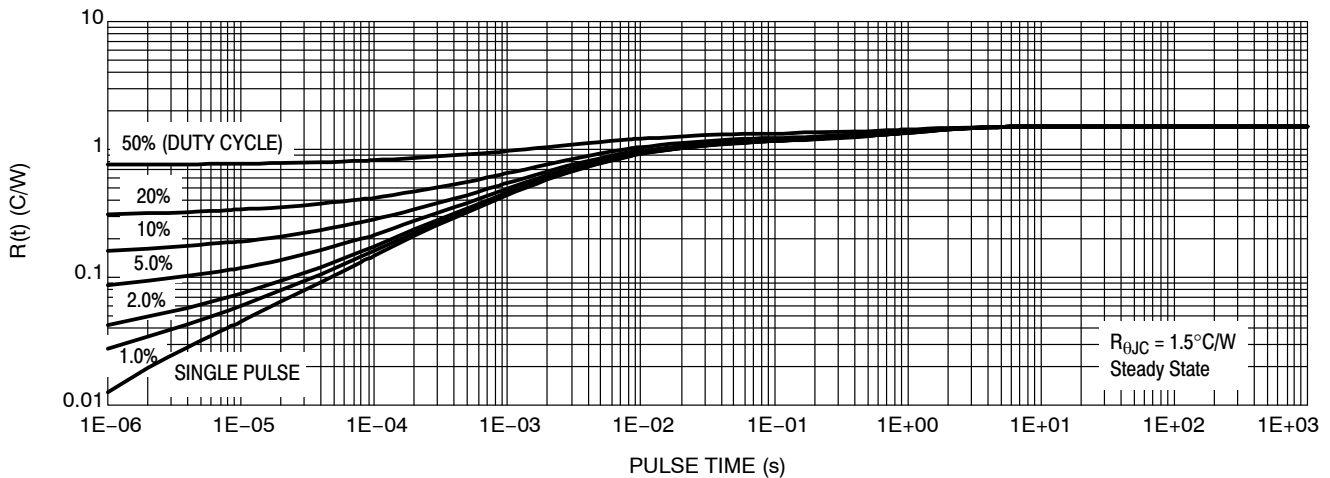
$V_{DS}$ , DRAIN-TO-SOURCE VOLTAGE (V)  
**Figure 12. Maximum Rated Forward Biased Safe Operating Area NDF05N50Z**



$V_{DS}$ , DRAIN-TO-SOURCE VOLTAGE (V)  
**Figure 13. Maximum Rated Forward Biased Safe Operating Area NDD05N50Z**



**Figure 14. Thermal Impedance (Junction-to-Case) for NDF05N50Z**



**Figure 15. Thermal Impedance (Junction-to-Case) for NDD05N50Z**

# NDF05N50Z, NDD05N50Z

## TYPICAL CHARACTERISTICS

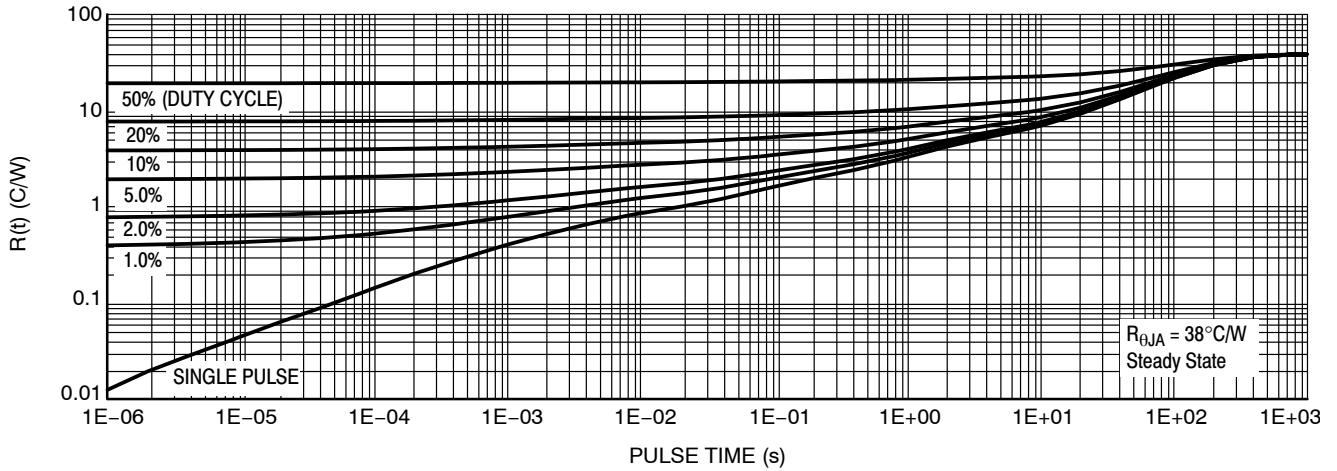


Figure 16. Thermal Impedance (Junction-to-Ambient) for NDD05N50Z

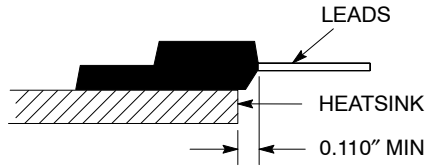


Figure 17. Isolation Test Diagram

Measurement made between leads and heatsink with all leads shorted together.

\*For additional mounting information, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

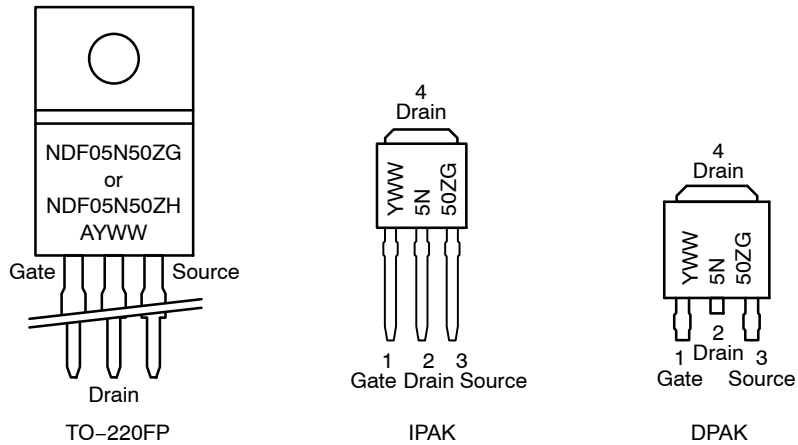
# NDF05N50Z, NDD05N50Z

## ORDERING INFORMATION

Order Number	Package	Shipping†
NDF05N50ZG	TO-220FP (Pb-Free, Halogen-Free)	50 Units / Rail
NDF05N50ZH	TO-220FP (Pb-Free, Halogen-Free)	50 Units / Rail
NDD05N50Z-1G	IPAK (Pb-Free, Halogen-Free)	75 Units / Rail
NDD05N50ZT4G	DPAK (Pb-Free, Halogen-Free)	2500 / Tape and Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## MARKING DIAGRAMS

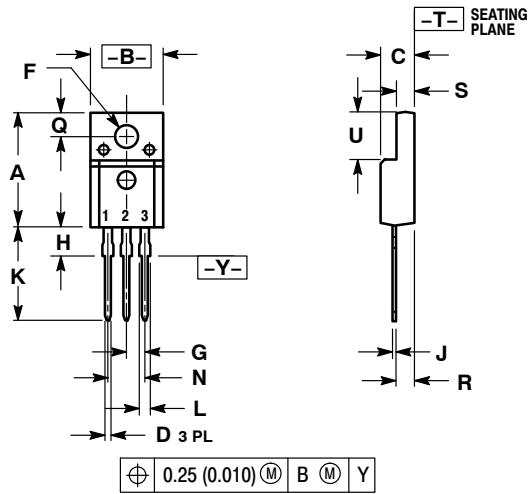


A = Location Code  
 Y = Year  
 WW = Work Week  
 G, H = Pb-Free, Halogen-Free Package

# NDF05N50Z, NDD05N50Z

## PACKAGE DIMENSIONS

TO-220 FULLPAK  
CASE 221D-03  
ISSUE K



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH
3. 221D-01 THRU 221D-02 OBSOLETE, NEW STANDARD 221D-03.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.617	0.635	15.67	16.12
B	0.392	0.419	9.96	10.63
C	0.177	0.193	4.50	4.90
D	0.024	0.039	0.60	1.00
F	0.116	0.129	2.95	3.28
G	0.100 BSC		2.54 BSC	
H	0.118	0.135	3.00	3.43
J	0.018	0.025	0.45	0.63
K	0.503	0.541	12.78	13.73
L	0.048	0.058	1.23	1.47
N	0.200 BSC		5.08 BSC	
Q	0.122	0.138	3.10	3.50
R	0.099	0.117	2.51	2.96
S	0.092	0.113	2.34	2.87
U	0.239	0.271	6.06	6.88

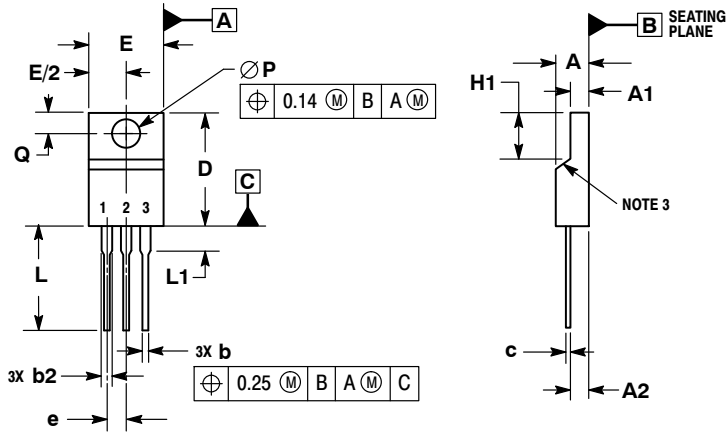
- STYLE 1:  
PIN 1. GATE  
2. DRAIN  
3. SOURCE



# NDF05N50Z, NDD05N50Z

## PACKAGE DIMENSIONS

TO-220 FULLPACK, 3-LEAD  
CASE 221AH  
ISSUE D



**NOTES:**

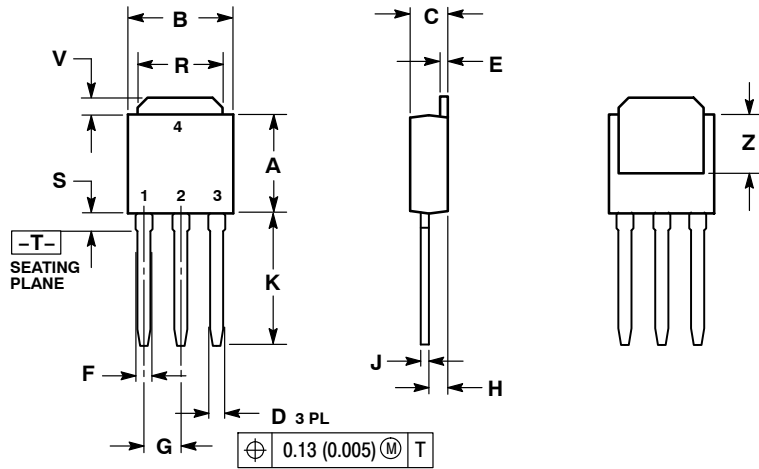
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. CONTOUR UNCONTROLLED IN THIS AREA.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH AND GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.13 PER SIDE. THESE DIMENSIONS ARE TO BE MEASURED AT OUTERMOST EXTREME OF THE PLASTIC BODY.
5. DIMENSION b2 DOES NOT INCLUDE DAMBAR PROTRUSION. LEAD WIDTH INCLUDING PROTRUSION SHALL NOT EXCEED 2.00.

DIM	MILLIMETERS	
	MIN	MAX
A	4.30	4.70
A1	2.50	2.90
A2	2.50	2.70
b	0.54	0.84
b2	1.10	1.40
c	0.49	0.79
D	14.70	15.30
E	9.70	10.30
e	2.54 BSC	
H1	6.70	7.10
L	12.70	14.73
L1	---	2.10
P	3.00	3.40
Q	2.80	3.20

# NDF05N50Z, NDD05N50Z

## PACKAGE DIMENSIONS

IPAK  
CASE 369D  
ISSUE C



- NOTES:  
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.  
2. CONTROLLING DIMENSION: INCH.

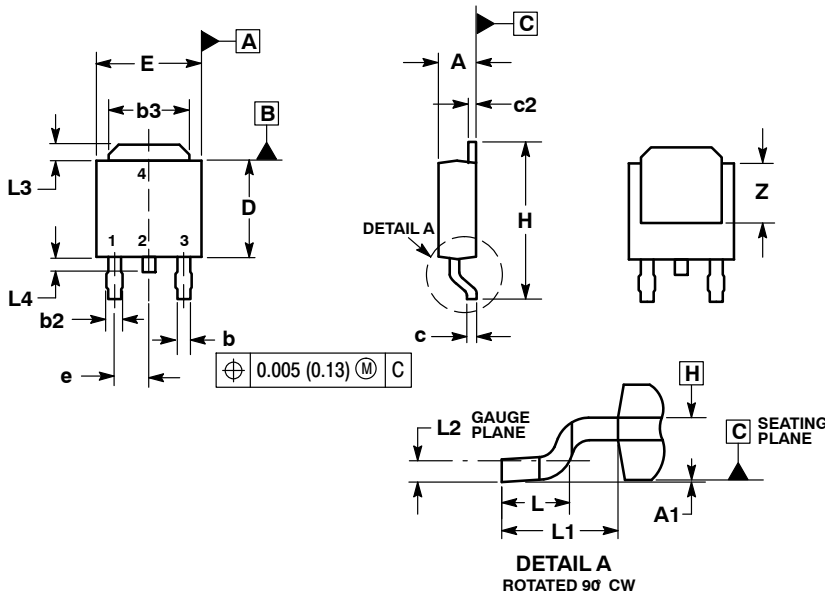
DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.235	0.245	5.97	6.35
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
E	0.018	0.023	0.46	0.58
F	0.037	0.045	0.94	1.14
G	0.090 BSC		2.29 BSC	
H	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.350	0.380	8.89	9.65
R	0.180	0.215	4.45	5.45
S	0.025	0.040	0.63	1.01
V	0.035	0.050	0.89	1.27
Z	0.155	---	3.93	---

- STYLE 2:  
PIN 1. GATE  
2. DRAIN  
3. SOURCE  
4. DRAIN

# NDF05N50Z, NDD05N50Z

## PACKAGE DIMENSIONS

### DPAK (SINGLE GAUGE) CASE 369AA ISSUE B

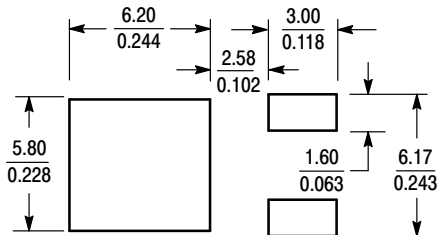


#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.030	0.045	0.76	1.14
b3	0.180	0.215	4.57	5.46
c	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
e	0.090	BSC	2.29	BSC
H	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.108	REF	2.74	REF
L2	0.020	BSC	0.51	BSC
L3	0.035	0.050	0.89	1.27
L4	---	0.040	---	1.01
Z	0.155	---	3.93	---

#### SOLDERING FOOTPRINT\*



SCALE 3:1  $\left(\frac{\text{mm}}{\text{inches}}\right)$

#### STYLE 2:

1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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